



HSEC8-DV SERIES

(0.80 mm) .0315"

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer Contact:

Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating: 2.8 A per pin

(2 adjacent pins powered)
Operating Temp:
-55 °C to +125 °C

RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (10-60)

RECOGNITIONS

CABLE CONNECTOR

ECDP-04 HSEC8-109-L2

ECDP-08 HSEC8-113-L2

FCDP-16 HSFC8-125-L2 ECDP-32 HSEC8-149-L2

For complete scope of recognitions see www.samtec.com/quality



Card Mates:

(1.60 mm) .062" card, (2.36 mm) .093" card, HSC8

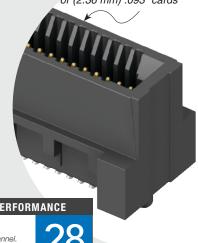
Cable Mates:

HSEC8

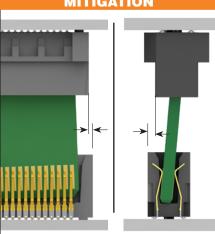


or (2.36 mm) .093" cards

Mates with (1.60 mm) .062"



MISALIGNMENT MITIGATION



Custom designs compensate for misalignment.

HIGH-SPEED CHANNEL PERFORMANCE

POSITIONS

PER ROW

No. of Positions x (0.80) .0315 + (7.80) .307

(No. of Positions + 6) x (0.80) .0315 + (0.60) .024

09, 13, 25, 37, 100

VERTICAL EDGE RATE® CARD SOCKET

HSEC8-DV

Rating based on Samtec reference channel For full SI performance data visit Samtec.com or contact SIG@samtec.com

CARD THICKNESS

PLATING **OPTION**

DV

OTHER OPTION

09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100

(13, 25, 49 only available with –L or –L2 option; 09 only available with -L2 option; 37 only available with -L option)

-01 (1.60 mm) .062" thick card -03 (2.36 mm) .093

thick card

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

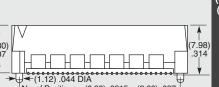
= 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail

PER ROW	Α	В
09*†	(4.50) .177	(11.80) .465
13*†	(6.10) .240	(15.00) .591
25*†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49*†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70†	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100†	(26.90) 1.059	(84.60) 3.331
Positions where no dimensions are given		

do not have keying feature

Mates with ECDP Series

.052



Pick & Place Pad (with -03 card) -BL

(7.01 mm) .276" DIA Polyimide Film Pick & Place Pad

(with –01 card) (6.25 mm) .246" DIA Polyimide Film

= Board Locks (-01 card only) (Weld tab standard)

= Latching Option (–01 card only) (13, 25, 37, 49 only) (Weld tab standard)

L2

= ECDP Latching (-01 card only) (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard)

> –WT = Weld tab

-TR =Tape & Reel (09 - 70 only)

No. of Positions x (0.80) .0315 + (4.60) .181 (7.00)^(5.60) .276 .220 .307 -(1.75) -(0.80) .0315 No. of Positions x (0.80) .0315 + (2.20) .087 070 10, 20 & 30

Due to technical progress, all designs, specifications and components are subject to change without notice

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non-returnable.

While optimized for 50 Ω

applications, this connector

Some lengths, styles and options are non-standard,

with alternative signal/ground

patterns may also perform well in certain 75 Ω applications.